

STN	Integrácia softvérového nástroja (FDI) Časť 4: Programové balíky FDI	STN EN IEC 62769-4 18 4012
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Field Device Integration (FDI) - Part 4: FDI Packages

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/21

Obsahuje: EN IEC 62769-4:2021, IEC 62769-4:2021

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Supersedes EN 62769-4:2015 and all of its amendments
and corrigenda (if any)

English Version

**Field Device Integration (FDI) - Part 4: FDI Packages
(IEC 62769-4:2021)**Intégration des appareils de terrain (FDI) - Partie 4:
Paquetages FDI
(IEC 62769-4:2021)Feldgeräteintegration (FDI) - Teil 4: FDI-Packages
(IEC 62769-4:2021)

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EN IEC 62769-4:2021 (E)**European foreword**

The text of document 65E/761/FDIS, future edition 2 of IEC 62769-4, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-4:2021.

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- latest date by which the national standards conflicting with the (dow) 2024-03-12 document have to be withdrawn

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61784-1	NOTE	Harmonized as EN IEC 61784-1
IEC 61784-2	NOTE	Harmonized as EN IEC 61784-2
IEC 62591	NOTE	Harmonized as EN 62591
IEC 62769-2	NOTE	Harmonized as EN 62769-2
IEC 62769-3	NOTE	Harmonized as EN 62769-3
IEC 62769-5	NOTE	Harmonized as EN 62769-5
IEC 62769-7	NOTE	Harmonized as EN 62769-7

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804		series Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804 series	
IEC 61804-5	2015	Function blocks (FB) for process control and electronic device description language (EDDL) - Part 5: EDDL Built-in library	EN 61804-5	2015
IEC 62769-1	-	Field Device Integration (FDI) - Part 1: Overview	EN 62769-1	-
IEC 62769-6	-	Field Device Integration (FDI) - Part 6: Technology Mapping	EN 62769-6	-
ISO/IEC 29500-2	2016	Information technology - Document description and processing languages - Office Open XML File Formats - Part 2: Open Packaging Conventions	-	-
ISO 639-1	-	Codes for the representation of names of languages - Part 1: Alpha-2 code	-	-
ISO 32000-1	-	Document management - Portable document format - Part 1: PDF 1.7	-	-
Extensible Markup Language (XML) 1.0	-	W3C Recommendation, available at < http://www.w3.org/TR/REC-xml/ >	-	-
XML Schema Definition Language (XSD) 1.1	-	W3C Recommendation, available at < http://www.w3.org/TR/xmlschema11-1/ >	-	-
ETSI EN 319 132-1	-	Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures	-	-
ETSI TS 101 733	-	Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAAdES)	-	-
FIPS 140-2	-	Security Requirements for Cryptographic Modules	-	-



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INTERNATIONAL STANDARD

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**Field device integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**



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INTERNATIONAL STANDARD

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**Field device integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool;
- b) digital signature now includes trusted timestamping for long-term validation of FDI Package;
- c) time stamp for device package signature.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/761/FDIS	65E/771/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in Figure 1.

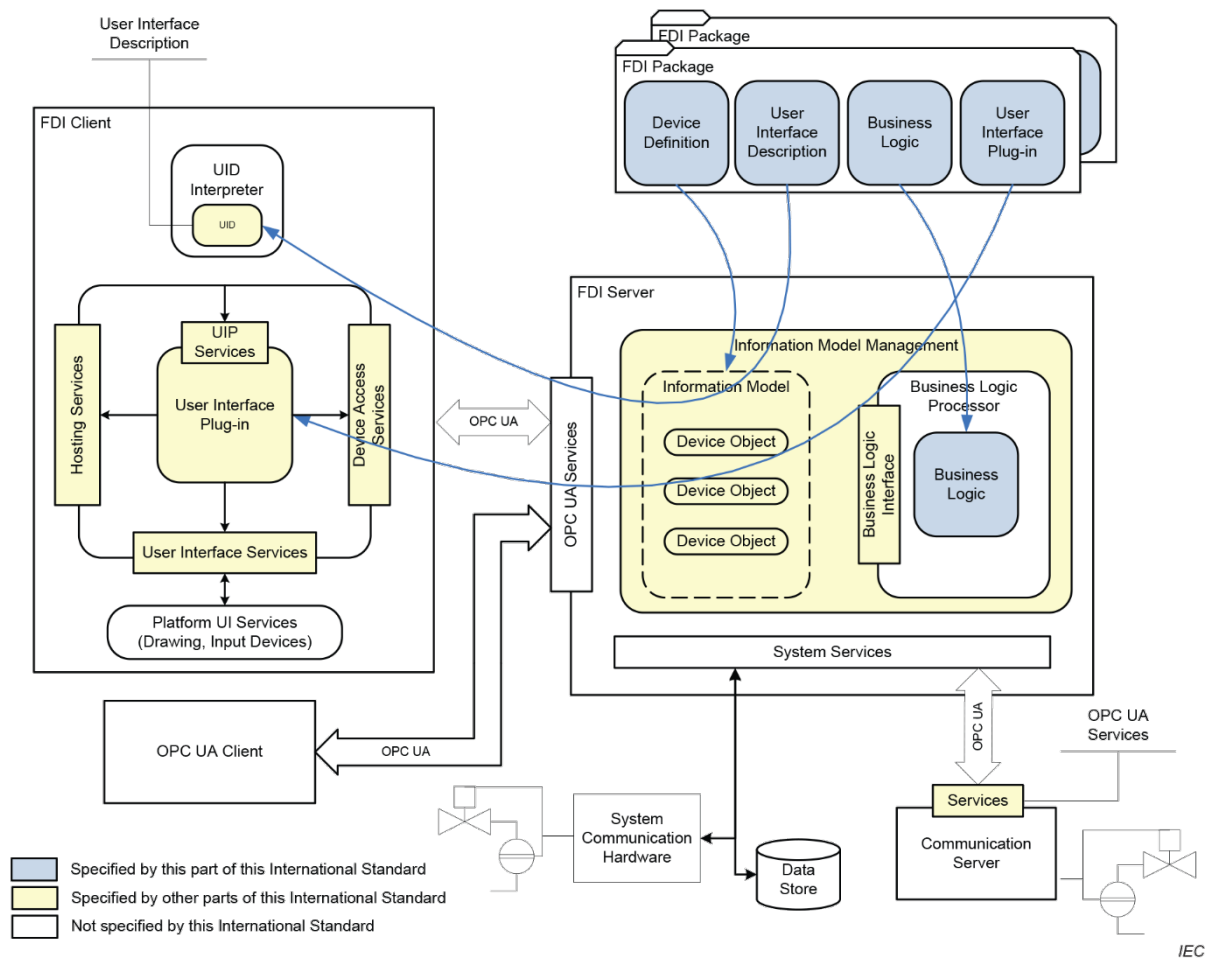


Figure 1 – FDI architecture diagram

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and electronic device description language (EDDL)*

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IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

ISO/IEC 29500-2:2016, *Information technology – Document description and processing languages – Office Open XML File Formats – Part 2: Open Packaging Conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

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